

SOT572-1

plastic low profile quad flat package; 100 leads; body 12 x 12 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP100
Package type industry code	LQFP100
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.9	-	12	12.1	mm
E	package width		11.9	-	12	12.1	mm
A	seated height		[tbd]	-	1.6	1.6	mm
A ₂	package height		1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination		-	-	100	-	



2. Package outline

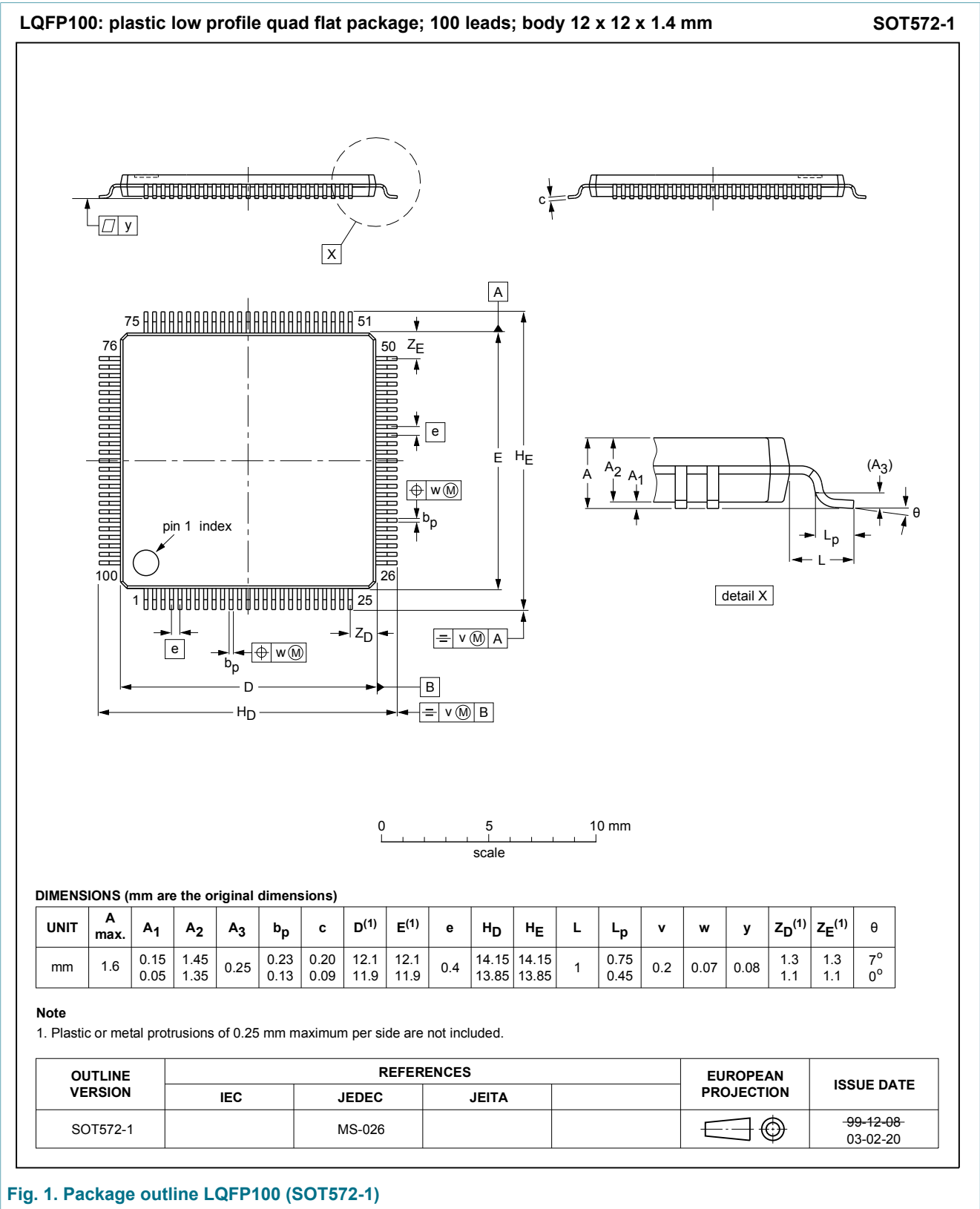


Fig. 1. Package outline LQFP100 (SOT572-1)

3. Soldering

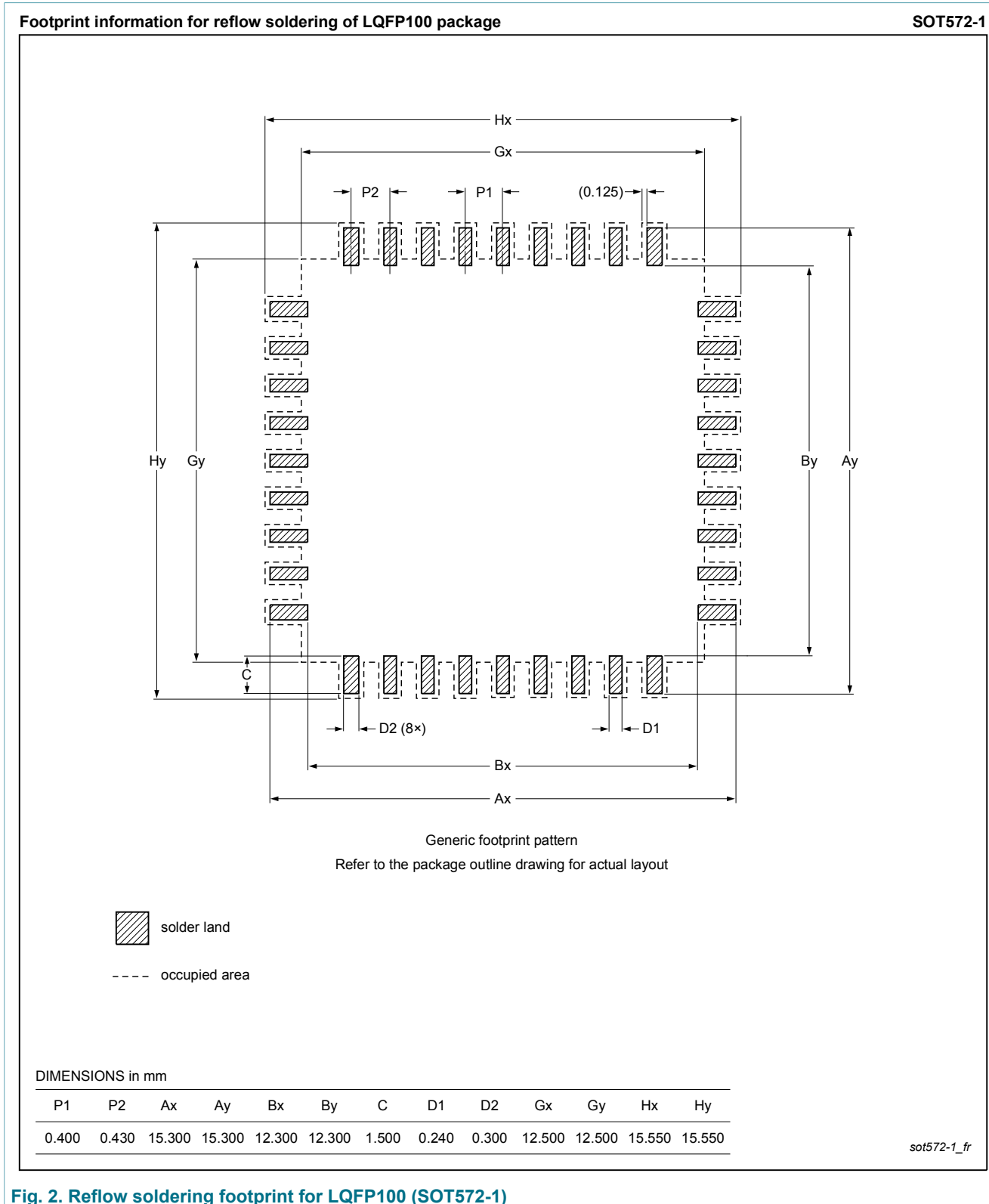


Fig. 2. Reflow soldering footprint for LQFP100 (SOT572-1)

4. Legal information

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